

Product / Package Information

Package	LFCSP
Body Size (mm)	3 X 3
Lead Count	12
Terminal Finish	100 Sn
MS Number	MS012326C

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	7.78E-03	93.7	937000	38.33		383321
Thermosets	Epoxy Resin	Proprietary	2.49E-04	3.0	30000	1.23		12273
Thermosets	Phenol Resin	Proprietary	2.49E-04	3.0	30000	1.23		12273
Other inorganic materials	Carbon Black	1333-86-4	2.49E-05	0.3	3000	0.12		1227
Subtotal			8.30E-03	100.00	1000000	40.91		409094

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	9.72 E-03	97.50	975000	47.86		478639
Copper & its alloys	Iron	7439-89-6	2.34 E-04	2.35	23500	1.15		11536
Copper & its alloys	Zinc	7440-66-6	1.20 E-05	0.12	1200	0.06		589
Copper & its alloys	Phosphorus	7723-14-0	2.99 E-06	0.03	300	0.01		147
Subtotal			9.97 E-03	100.00	1000000	49.09		490912

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.49 E-05	100.0	1000000	0.12		1227

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	4.75 E-04	100.0	1000000	2.34		23377

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	4.75 E-05	100.0	1000000	0.23		2338

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Gallium Arsenide	1303-00-0	1.42 E-03	100.0	1000000	7.01		70130

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	4.78 E-05	80.50	805000	0.24		2352
Other organic materials	Carbocyclic Acrylates	Proprietary	5.93 E-06	10.00	100000	0.03		292
Other organic materials	Bismaleimide resin	Proprietary	1.78 E-06	3.00	30000	0.01		88
Other organic materials	2-preponoic acid, 2-methyl	68586-19-6	1.78 E-06	3.00	30000	0.01		88
Others	Additive	Proprietary	1.78 E-06	3.00	30000	0.01		88
Other organic materials	Dicumyl peroxide	80-43-3	2.97 E-07	0.50	5000	0.00		15
Subtotal			5.93 E-05	100.00	1000000	0.29		2922

Package Totals			Weight (g) 2.03 E-02			Percentage (%) 100		PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge.
 DI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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